

LISTING OF THE CLAIMS

The present listing of claims replaces all prior versions.

Claims 1 -7 Cancelled

Claim 8. (Previously Presented) Dip soldering apparatus comprising:

a reservoir for molten solder;

an elongate plate provided in the reservoir and positioned at a surface of the molten solder, and surface component leads selectively movable between a raised and lowered condition for being dipped into said solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder; and

means for lowering the solder surface in order to effect withdrawal of the component leads from the solder.

Claim 9. (Currently Amended) Dip soldering apparatus comprising:

a nozzle having an outlet through which solder is flowed in use, and leads to be soldered selectively removable between a raised and lowered condition for being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered; and

means for lowering the solder surface in order to effect withdrawal of the component

leads from the solder;

wherein the member is positioned so as to project through the solder surface as the leads are withdrawn from the solder;

wherein means is provided to lower the solder surface to effect withdrawal of the leads from the solder.

Claim 10. (Previously Presented) Apparatus as claimed in claim 9, wherein the member is below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 11. (Previously Presented) Apparatus as claimed in claim 9, wherein the member is movable relative to the solder surface.

Claim 12. Cancelled

Claim 13. Cancelled

Claim 14. (Previously Presented) Apparatus as claimed in claim 9, wherein the member is an elongated plate having an upward/y facing edge.

Claim 15. (Previously Presented)) Apparatus as claimed in claim 9, wherein the member has a honeycomb structure.

Claims 16 - 18 Cancelled

Claim 19. (Previously Presented) The apparatus of claim 9 , wherein the member has a honeycomb structure.

Claim 20 (Previously Presented) Dip soldering apparatus comprising:

a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered; and means for lowering the solder surface in order to effect withdrawal of the leads from the solder;

wherein said member is movable relative to said solder surface.

Claim 21. (Previously Presented) The apparatus of claim 20, wherein said member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 22. (Previously Presented) The apparatus of claim 20, wherein said member is positioned in order to project through the solder surface as said component leads are withdrawn from the solder.

Claims 23. – 24 Cancelled

Claim 25 (Previously Presented) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered;

said apparatus further including means for lowering the solder surface in order to effect withdrawal of the leads from the solder; and

means for lowering the solder surface for effecting withdrawal of the component leads from the solder.

Claim 26. (Previously Presented) The apparatus of claim 25, wherein said member is disposed below the level of the solder surface as the solder flows through the nozzle outlet.

Claim 27. (Previously Presented) The apparatus of claim 25, wherein said member is movable relative to the solder surface.

Claim 28. (Previously Presented) The apparatus of claim 25, wherein said member is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

Claim 29. (Previously Presented) Dip soldering apparatus comprising:
a reservoir for molten solder;
an elongate plate provided in the reservoir and positioned at a surface of the molten solder, and surface component leads for being dipped into said solder, the plate having an

upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder; and

means for lowering the solder surface for effecting withdrawal of the component leads from the solder;

wherein said plate is movable relative to the solder surface.

Claim 30. (Previously Presented) The apparatus of claim 29, wherein said plate is positioned for projecting through the solder surface as the leads are withdrawn from the solder.

Claim 31. Cancelled

Claim 32. (Previously Presented) Dip soldering apparatus comprising:

a reservoir for molten solder;

an elongate plate provided in the reservoir and positioned at a surface of the molten solder, surface component leads for being dipped into said solder, the plate having an upwardly facing edge and side surfaces extending downwards from the plate edge, the plate being positioned and dimensioned so that adjacent component leads to be soldered pass to each side of the plate edge and the plate surface being of a material which is wetted by the molten solder;

said apparatus further including means for lowering the solder surface for effecting withdrawal of the leads from the solder ; and means for lowering the solder surface for effecting withdrawal of the component leads from the solder.

Claim 33. (Previously Presented) The apparatus of claim 32, wherein said plate is movable relative to the solder surface.

Claim 34. (Previously Presented) The apparatus of claim 32, wherein said plate is positioned for projecting through the solder surface as said component leads are withdrawn from said solder.

Claim 35. (Previously Presented) Dip soldering apparatus comprising a nozzle having an outlet through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein the nozzle includes a member provided at the nozzle outlet and having a surface which is wetted by the solder, the surface being positioned so as to be straddled by two adjacent leads of a component to be soldered; and

means for lowering the solder surface for effecting withdrawal of the component leads from the solder;

wherein said member has a honeycomb structure.